

ETROC: ETL ReadOut Chip for CMS MTD

→ with few comments on future precision timing & position detector R&D or challenges ahead

Ted Liu (Fermilab)

March 19th, CPAD

Panel Discussion on Fast Electronics for Timing Detectors

ETROC bump-bonded to LGAD,
To handle 16x16 pixels
Each 1.3 mm x 1.3 mm

Requirement:
ASIC contribution to
time resolution < ~40ps
L1 buffer latency: 12.5 us
65nm

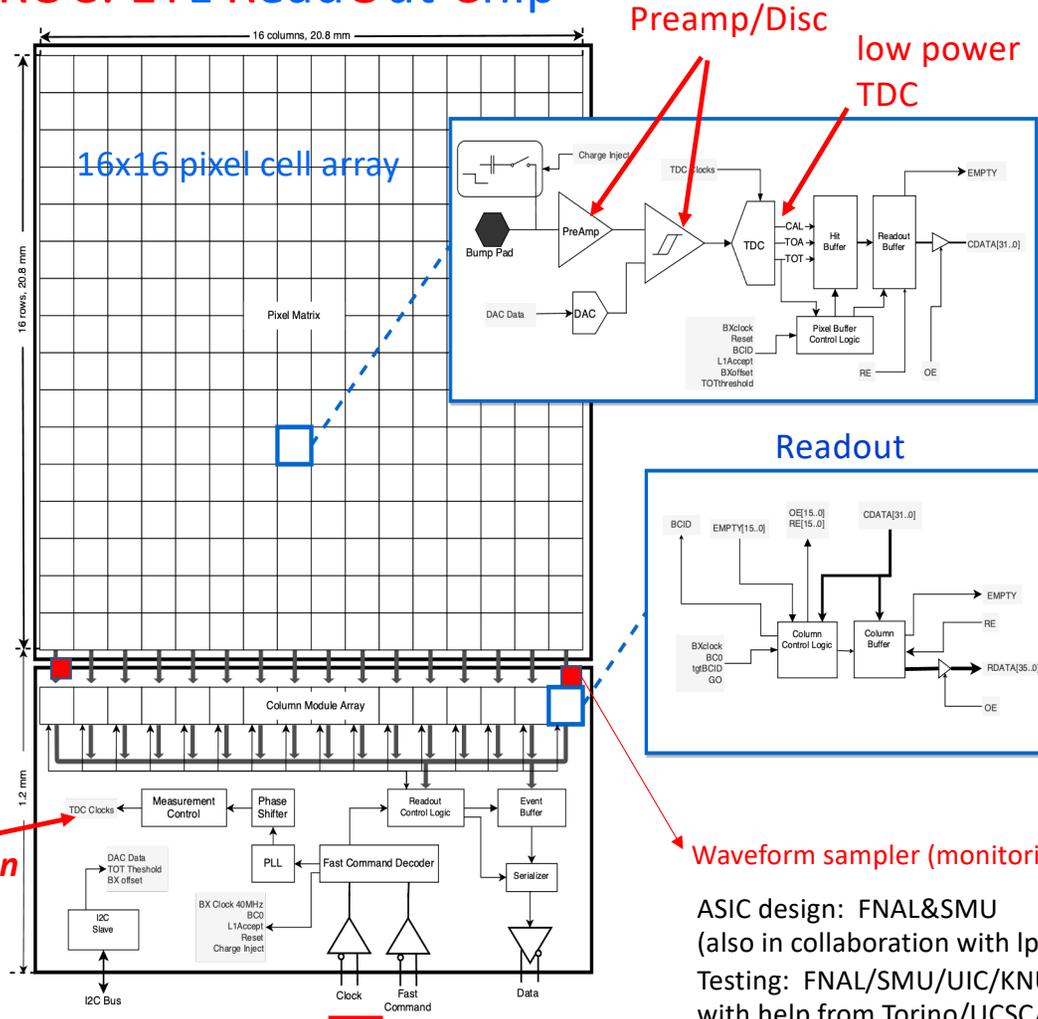
Main challenge:

Deal with small signal size
(down to ~6fC, at end of operation)
Low power consumption < 1W/chip
(about ~2-3mW/pixel)



clock distribution
all the way
into each pixel

ETROC: ETL ReadOut Chip



Ted Liu, ETROC

ETROC Development: *divide & conquer*

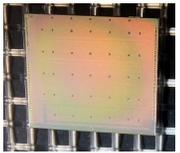
ETROC0: 1x1 pixel channel with preamp + discriminator (submitted Dec 2018)



The first prototype chip works well and agrees with simulation
~10ps achieved with charge injection, passed 100MRad TID testing
~30ps achieved in beam test with preamp waveform

ETROC1: 4x4 clock tree, preamp + discriminator + TDC (submitted Aug 2019)

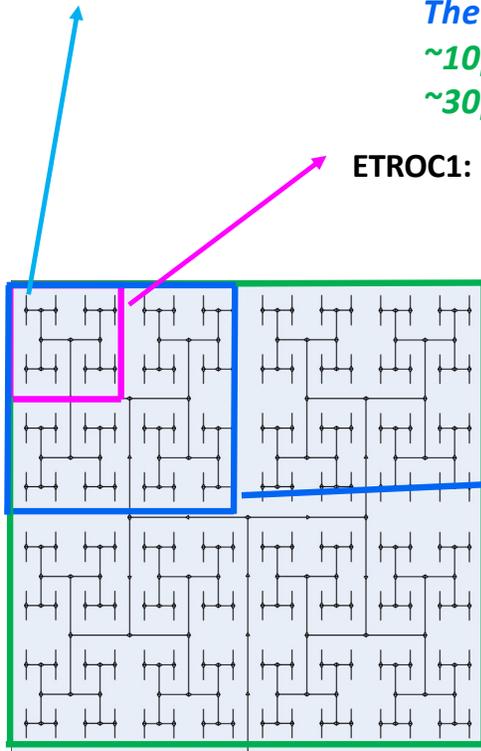
The first full chain precision timing prototype
Standalone ETROC1 charge injection testing works well and agree with simulation: The full chain and new TDC and the 4x4 clock tree
~10ps achieved with full chain and over 4x4 array
Bump bonded with LGAD sensor: bema test on going



ETROC2: 8x8 → 16x16, the first full size and full functionality prototype

Design on going, to be ready by end of 2020
ETROC2 PLL prototype works well
ETROC2 Waveform sampler prototypes works well
The main digital design implemented in FPGA emulator

ETROC3: 16x16 (full size & full functionality)

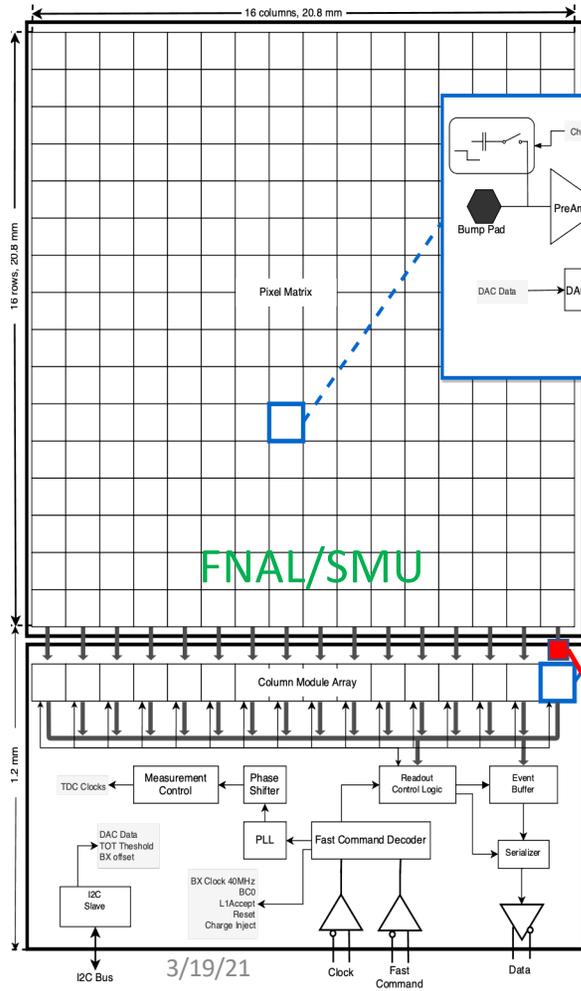


16 x 16 clock H-Tree distribution

We have followed this plan since the project started (Sept. 2018) ...

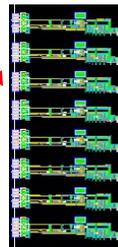
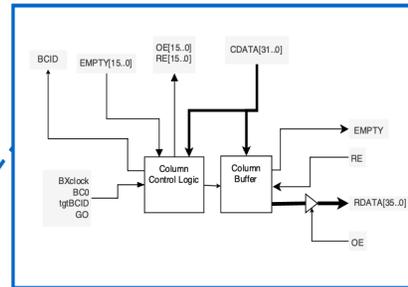
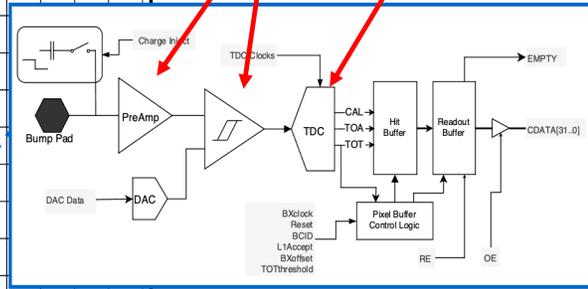
ETROC building blocks vs sizes (65 nm)

16x16 pixel cell array (1.3mm x 1.3 mm)



Preamp/Disc

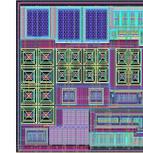
low power TDC



300um x 800um

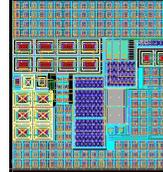
3.2GS/s waveform sampler

81 um X 67 um



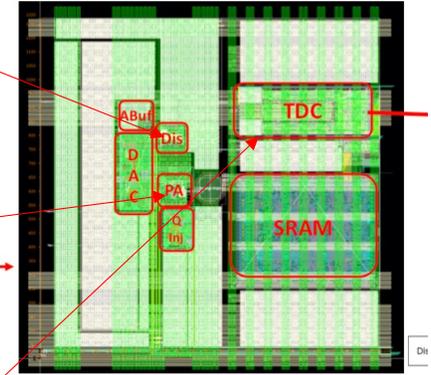
Discriminator

90 um X 94 um

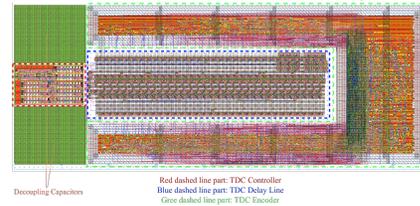


Preamp

ETROC1 Single Pixel Layout
1.3 mm x 1.3mm



TDC 467 um X 166 um



For future R&D:

1.3mm x 1.3mm to ~ 100 um x 100um:

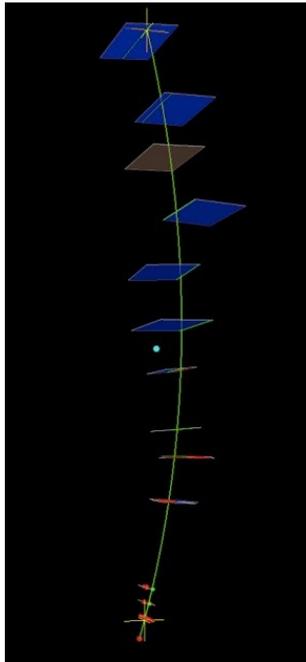
a factor of ~170 in pixel size, also power budget if ~1W/chip is still the budget, perhaps also clock distribution by no means straightforward ...

Need to think very hard on system design at all levels to relax ASIC requirements (detector layers, more power/cooling budget, larger pixel size, charge sharing, 28nm/beyond and 3DIC)

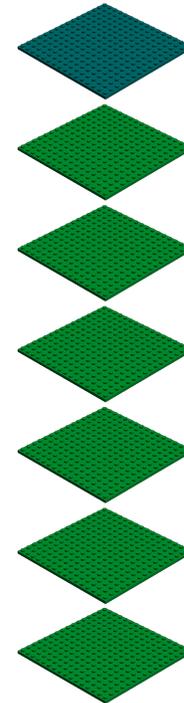
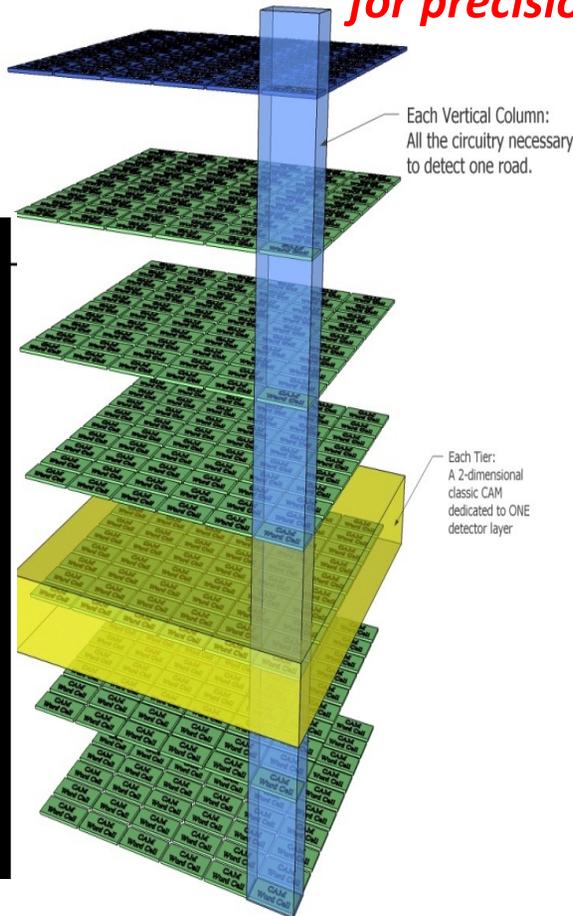
Ted Liu, ETROC

3DIC Technology

Earlier multi-tier stacking concept for pattern recognition



How could 3DIC help to scale to smaller pixel size for precision position & timing detectors



An open flexible architecture for precision position and timing detector
(one example below)



- readout and interfaces
- Hit buffer
- TDC and Clock distribution
- preamp/discriminator
- Sensor pixels (~100 um x ~ 100um each)

3DIC allows repartition of the design blocks vertically for the whole signal processing chain... also allows combination of different technologies... to combine the best of the world (e.g. front-end)

3DIC is promising in the future. For near future, more realistic approach is perhaps to keep the pixel size not too small (a few 100 um x a few 100 um), relax timing requirement per hit, relax power constraint ...

“A New Concept of Vertically Integrated Pattern Recognition Associative Memory”
<http://www.sciencedirect.com/science/article/pii/S1875389212019165>

Backup slides

ETROC power consumption update (TDR/simulation/measured)

Final ETROC0/1 design simulation results vs measured

Circuit component	Power per channel [mW]	Power per ASIC [mW]
Preamplifier (low-setting)	0.67 0.76 0.74	171.5 190
Preamplifier (high-setting)	1.25 1.31 1.27	320 325
Discriminator	0.71 0.87 0.84	181.8 215
TDC	0.2 0.07 0.1	51.2 26
SRAM	0.35 0.25 (new)	89.6 64
Supporting circuitry	0.2 0.2 (reserve)	51.2 51
Global circuitry		200 226.5
Total (low-setting)	2.13 2.13	745 773
Total (high-setting)	2.71 2.66	894 908
Total (highest setting)		2.91 972

We are still within
1W/chip spec

- Measurements agree with simulation of ETROC0 and 1 design
 - TT corner numbers shown, mostly agree reasonably well
 - TDC power is assuming 1% occupancy....
 - At 10% occupancy, from 0.1mW to 0.32mW (0.22mW x 256 = 56mW)
 - Will need to add 56mW to the total power IF 10% TDC occupancy.

Overall expected ETROC performance

Time resolution

LGAD+ preamp/discriminator + TDC bin	35 ps
Time-walk correction residual	< 10 ps
Internal clock distribution	< 10 ps
System clock distribution	< 15 ps
Per hit total time resolution	41 ps
Per track (2 hits) total time resolution	29 ps

40/46



being verified with ETROC1

45/50

**With safety margin:
design specification is
~ 35ps per track (~50ps per hit),
< ~ 60ps per track at end of life
(~80 ps per hit)**

32/35

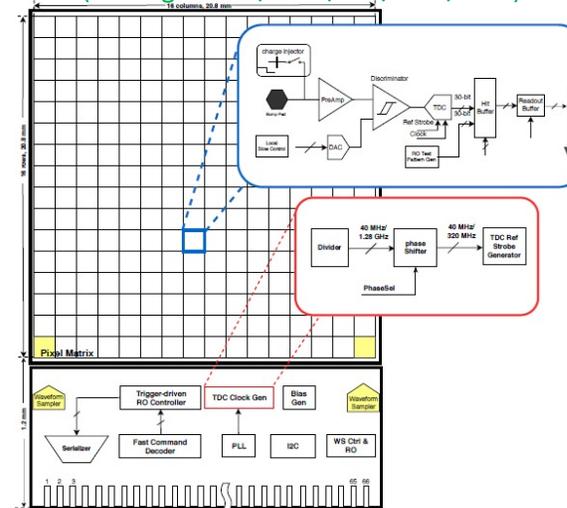
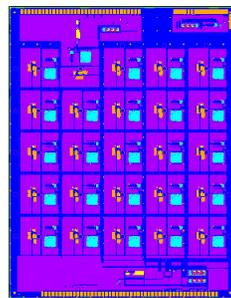
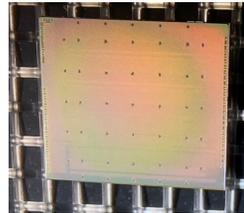
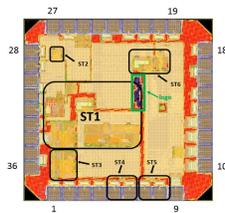
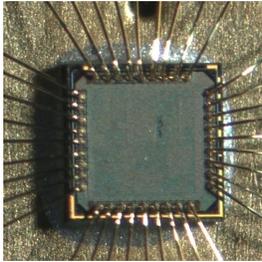
Power consumption (TDR)

Circuit component	Power per channel [mW]	Power per ASIC [mW]
Preamplifier (low-setting)	0.67	171.5
Preamplifier (high-setting)	1.25	320
Discriminator	0.71	181.8
TDC	0.2	51.2
SRAM	0.35	89.6
Supporting circuitry	0.2	51.2
Global circuitry		200
Total (low-setting)	2.13	745
Total (high-setting)	2.71	894

**With some safety margin:
design specification is
~ 1W per chip**

From ETROC0 to ETROC1 to ETROC2/3

ASIC designers from FNAL/SMU
& in collaboration with IpGBT team
(Testing: FNAL/SMU/UIC/KNU/CNU)



ETROC0

- Submitted in Dec. 2018
- Analog Front-end
- First round beam test early 2020, reached ~30ps
- good

ETROC1

- Submitted in Aug. 2019
- 4 X 4 pixel array with full front-end including TDC
- Chips received middle Dec 2019
 - TDC block: good
 - Full chain standalone: good
 - Beam test: just started

ETROC2

- Aim to submit by end of 2021
- Designed to be compatible with 16 X 16 pixel array with full functionalities
- Key new design blocks:
 - Waveform sampler:
 - 1st ADC mini-ASIC good
 - 8-channel sampler chips received in May 2020 good
 - PLL: submitted in May 2020
 - Good, passed SEU

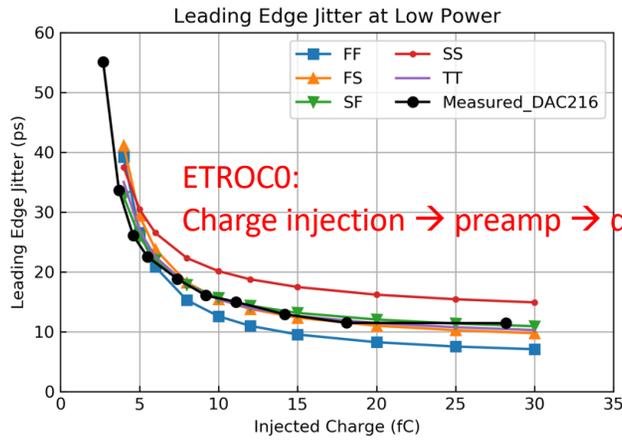
ETROC3

- Aim to submit in 2022
- Pre-production version

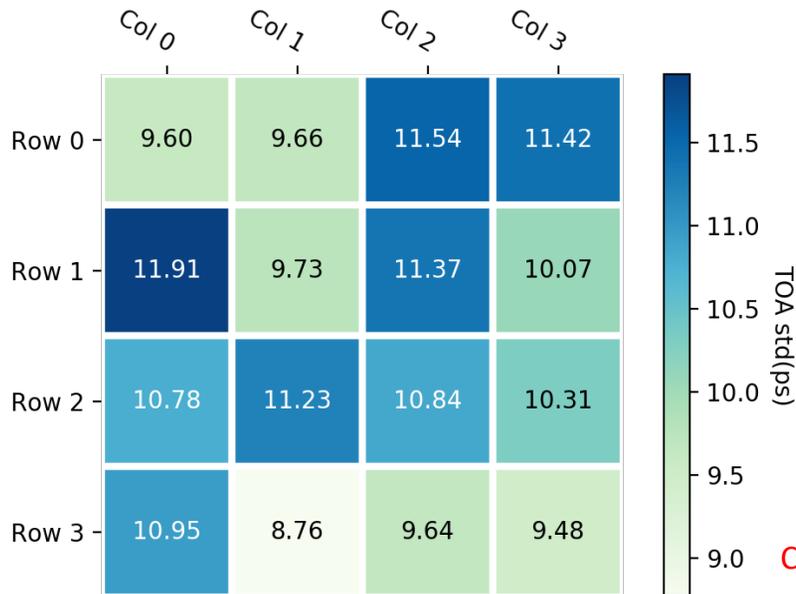
Since project started Sept 2018,
Designed 5 different kinds of prototype chips
to address different design challenges:

All successful status

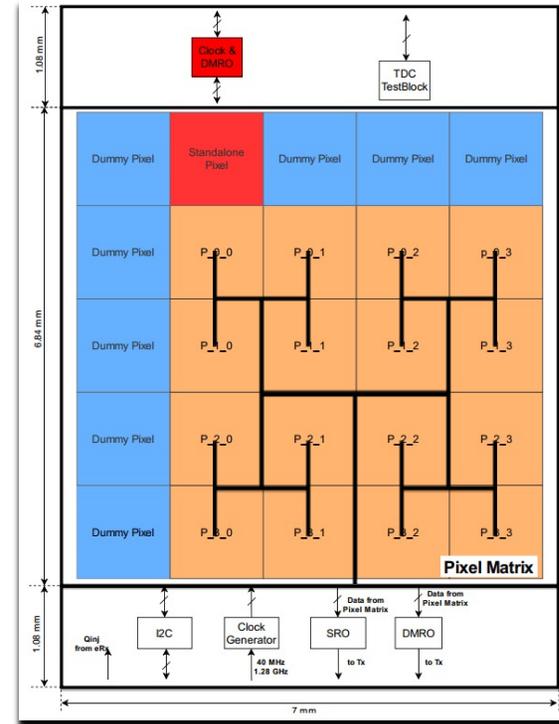
Jitter measurements with charge injection



ETROCO:
Charge injection → preamp → discriminator → scope



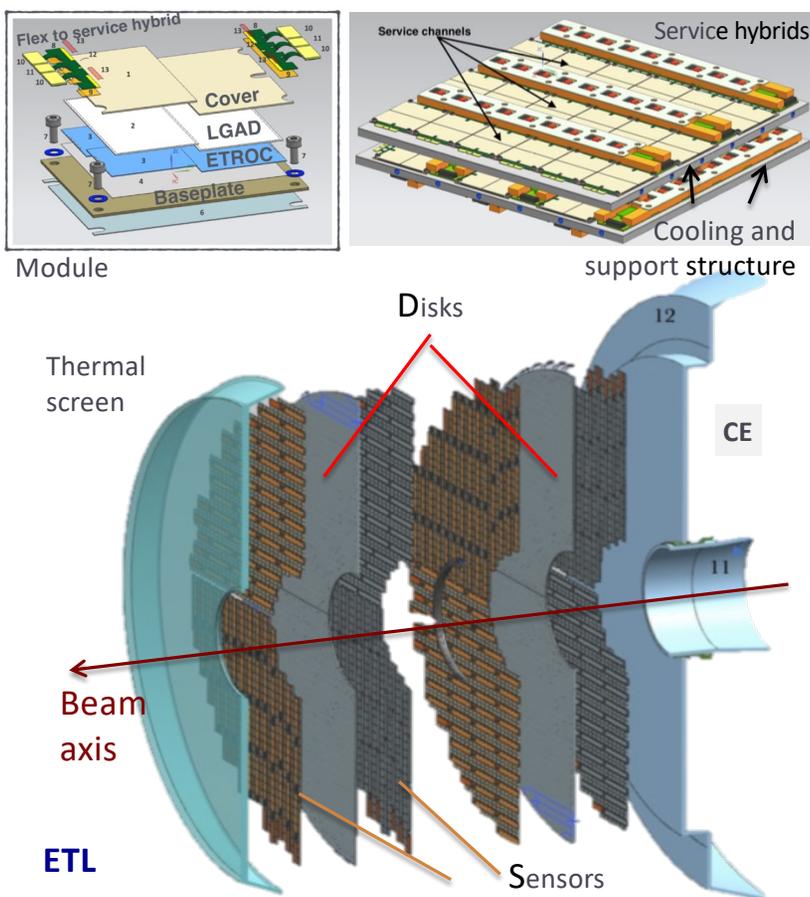
with bare ETROC1



ETROC1 4x4 clock (H) tree

Charge injection → preamp → discriminator → TDC

ETL precision timing *challenges*



- Low Gain Avalanche Detectors (LGADs)
 - Basic unit: Module (4x6 cm²)
 - 2x4 cm² LGAD bump-bonded to 2 ETROC ASICs mounted on two sides of cooling plates
 - Two layers/disks per endcap mounted on the HGC nose (~2 hits per track)
 - 50ps per hit → 35ps per track
 - 1.6 < |η| < 3.0, +- 3m surface ~14 m²; ~8.5 M channels
 - Nominal fluence: $1.6 \times 10^{15} n_{ec}/cm^2$ (@ 3000 fb⁻¹)
- LGAD gain modest: 10-30
 - Landau contribution: ~ 30-40ps
 - Front-end contribution kept < ~40ps
- **Extract precision timing from small LGAD signal (6fC – 20fC) at end of operation**
With low power: < 4mW/channel

ASIC design: The System Point of View

ASIC: Application Specific Integrated Circuit

ASIC: A System design that Includes a Chip

Proper System Design is the Key to the success of any challenging ASIC project

A good design is a compromise between system design and ASIC design

Design aspects for precision timing detector

- Design methodology to optimize front-end design from system point of view
- Single layer detector vs multi-layer (ETL design: 1 layer → 2 layer)
- System power and cooling constraint and how it influences ASIC design
- Precision clock distribution considerations: from system to detector, to chip, to pixel and to each TDC delay unit
- Design for monitoring and calibration considerations
- Time-frame of ASIC development: “several miniASICs vs. single full ASIC”
- ...

Will not have time to get into these

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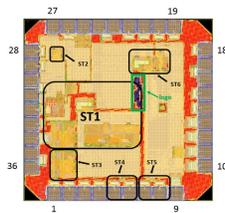
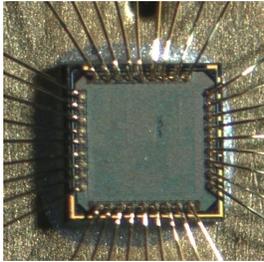
ETROC status

- ETROC0
 - Charge injection **done**
 - Cosmic **done**
 - Laser testing **done**
 - TID test to 100Mrads **done**
 - Beam testing **~30ps achieved in beam**
- ETROC1 (good progress made despite COVID this year)
 - TDC extensively tested: **excellent performance (<~6ps resolution)**
 - Full array full chain ETROC1 charge injection testing: **results good**
 - ETROC1 and 5x5 LGAD sensor **bump-bonded**
 - **Laser testing followed by beam testing (Feb – April 2021)**
- ETROC2
 - PLL mini-ASIC: **initial test results good**
 - Waveform sampler prototype: **works well**
 - ETROC emulator: **design completed, firmware advanced**
 - **Fast command decoding, pixel DAQ readout, system interfaces**
 - **The main digital blocks being prototyped in the emulator**
 - **Clock tree: from ETROC1 4x4 to ETROC2 16x16**

Only a few highlights shown in the talk Due to limited time.

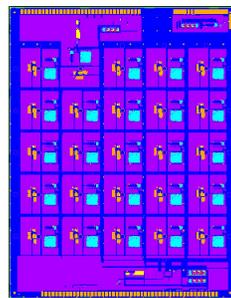
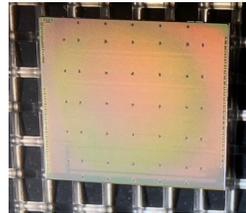
From ETROC0 to ETROC1 to ETROC2/3

ASIC designers from FNAL/SMU
& in collaboration with IpGBT team
(Testing: FNAL/SMU/UIC/KNU)



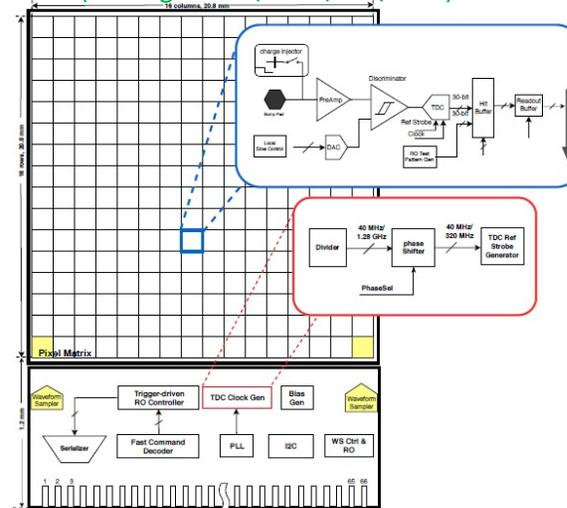
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- Analog Front-end
- First round beam test early 2020, reached ~30ps
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ETROC1

- Submitted in Aug. 2019
- 4 X 4 pixel array with full front-end including TDC
- Chips received middle Dec 2019
 - TDC block: good
 - Full chain: good
 - Laser: started



ETROC2

- Aim to submit in Aug 2021
- Designed to be compatible with 16 X 16 pixel array with *full functionalities*
- Key new design blocks prototyped
 - Waveform sampler:
 - 1st ADC mini-ASIC good
 - 8-channel sampler chips good
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ETROC3

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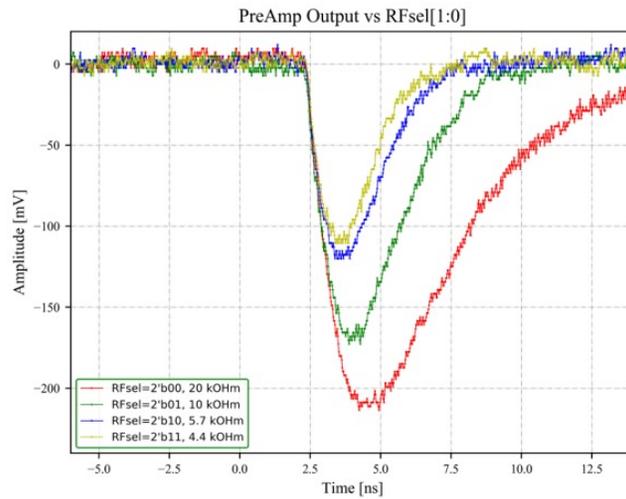
All successful

ETROCO summary

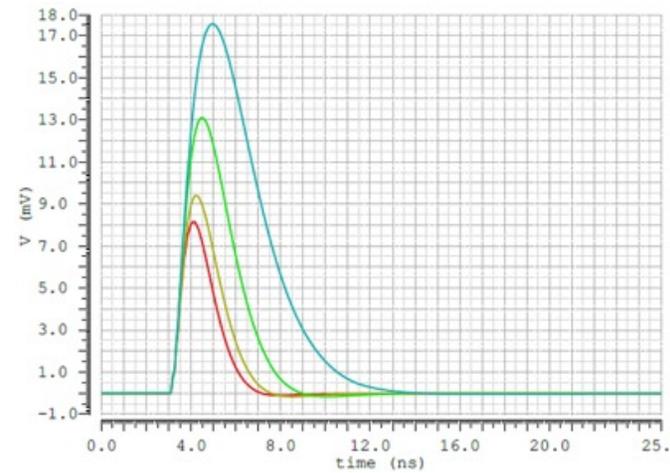
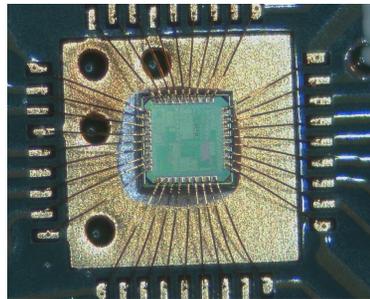
- Design started Sept 2019, submitted Dec 2019
 - *Only three months: design implementation/verification*
 - *Design was optimized using LGAD simulation from Nicolo*
 - *For charge from ~20 fC down to 6 fC, or LGAD gain down to ~10*
- ETROCO Testing:
 - Charge injection done
 - Cosmic done
 - Laser testing done
 - TID test to 100Mrads done (all good)
 - Beam testing ~30ps achieved (waveform analysis)
 - Achieved with two independent setups

See backup slides for some details (53-60)

ETROC0 preamp output waveform with charge injection



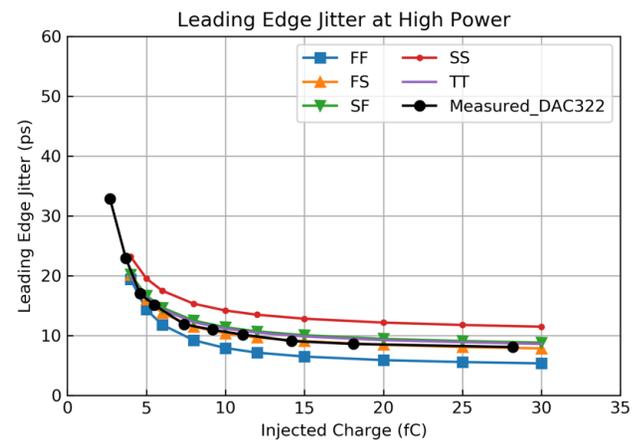
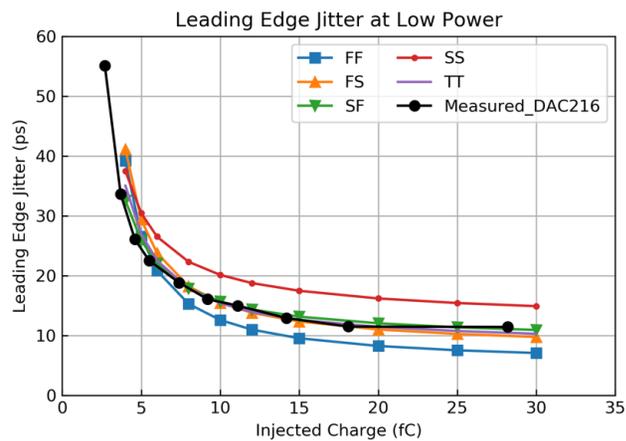
Measured waveforms at the output of the amplifier
Gain of external amplifier: -10



simulated waveforms at the output of the on-chip analog buffer
The analog buffer has a typical gain about 0.7

ETROC0 jitter: measured vs simulation

ETROC0 post-layout simulation vs testing results using 25ps risetime external pulse injection



ETROC0: Preamp + discriminator

Summary of the charge injection testing:

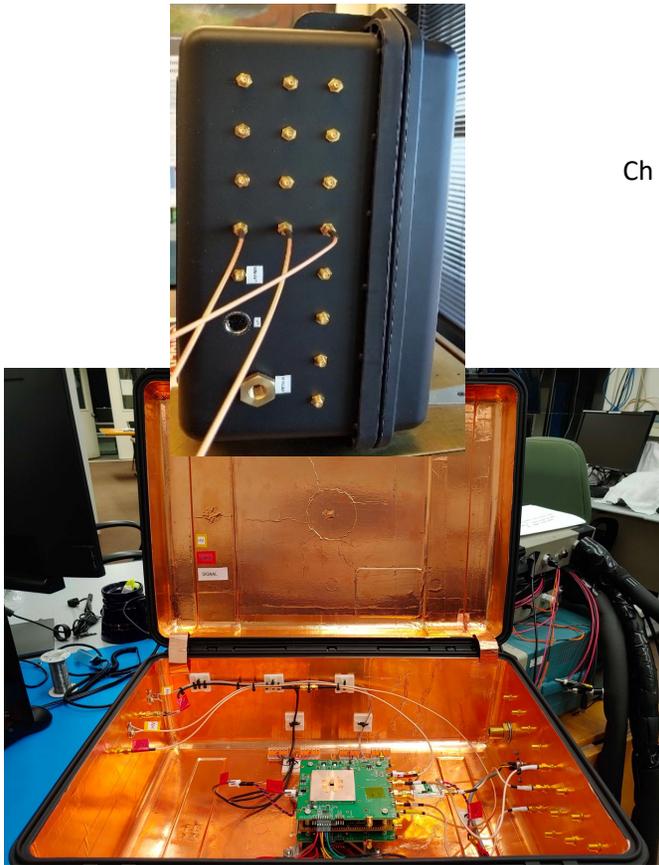
Discriminator leading edge jitter measurements agree with chip post-layout simulation

Power consumption for preamp and discriminator all match with simulation

A simple ETROCO Beam Telescope (3 boards)

Jan-Feb 2020

Simple "suitcase" setup in parasitic mode running at FNAL MTest



Ch 3 2 1

120 GeV proton Beam

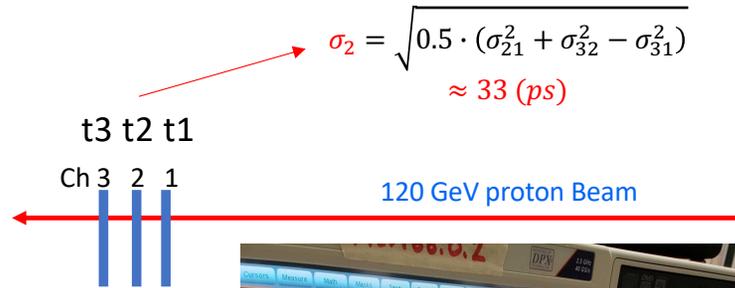


A simple Beam Telescope (with 3 HPK-ETROCO boards)

Jan-Feb 2020

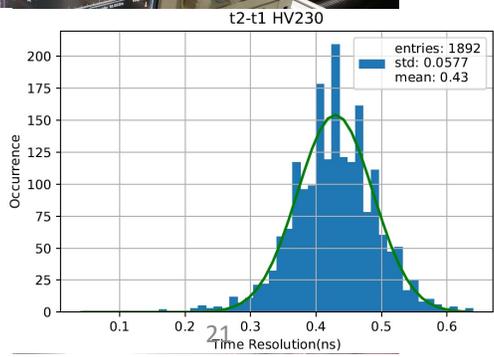
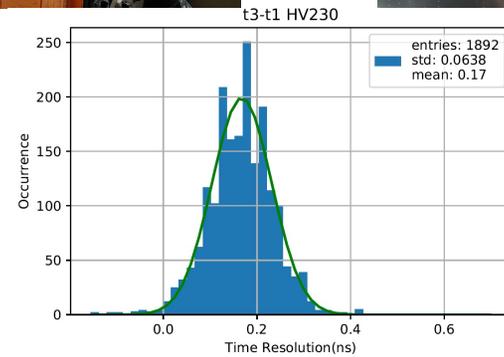
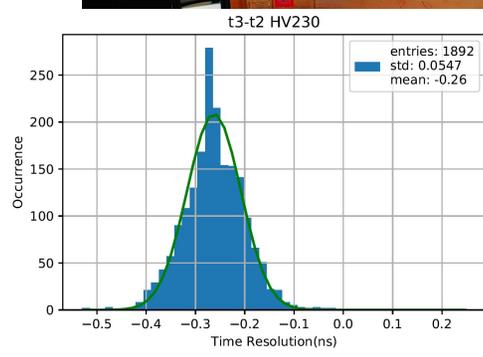
Simple "suitcase" setup in parasitic mode running at FNAL MTest

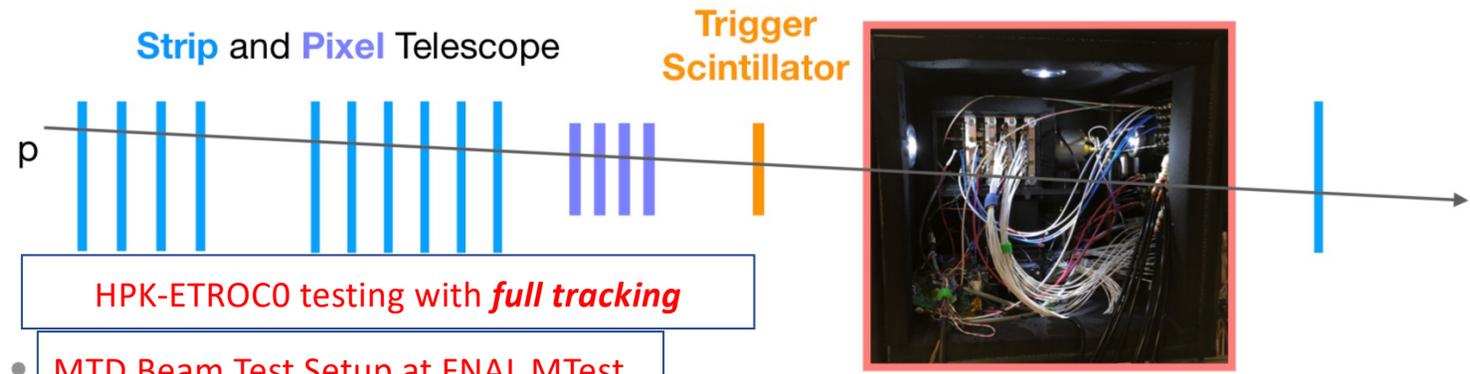
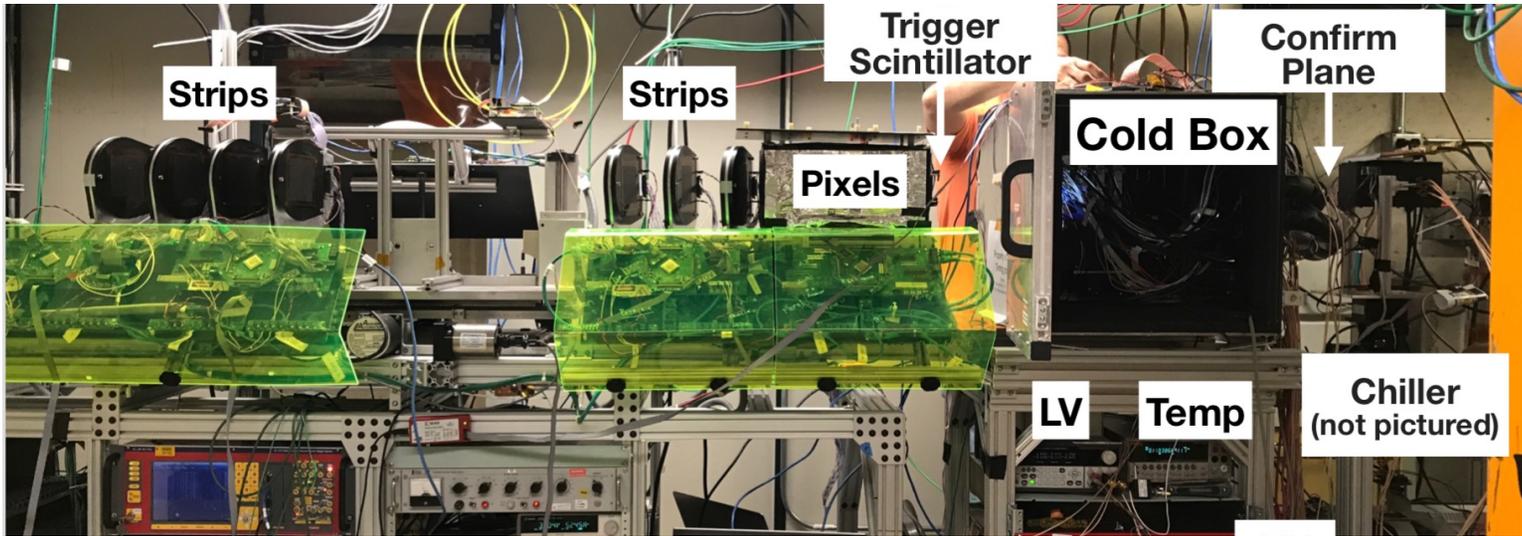
April – May 2020
parasitic run
cancelled due to
COVID-19



$$\sigma_2 = \sqrt{0.5 \cdot (\sigma_{21}^2 + \sigma_{32}^2 - \sigma_{31}^2)}$$

$\approx 33 \text{ (ps)}$

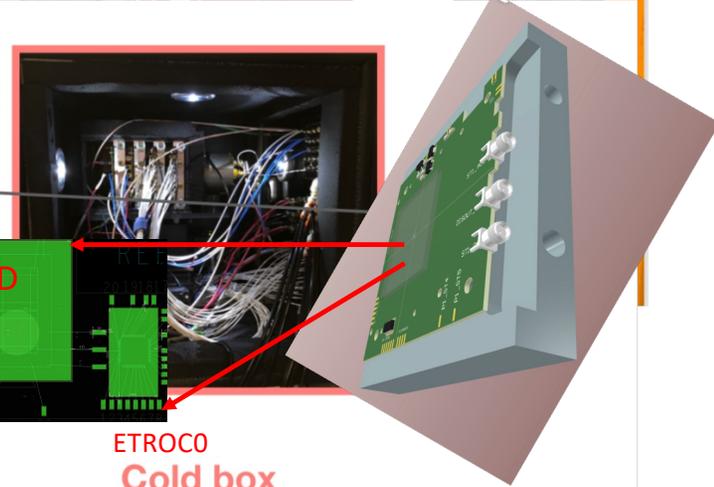
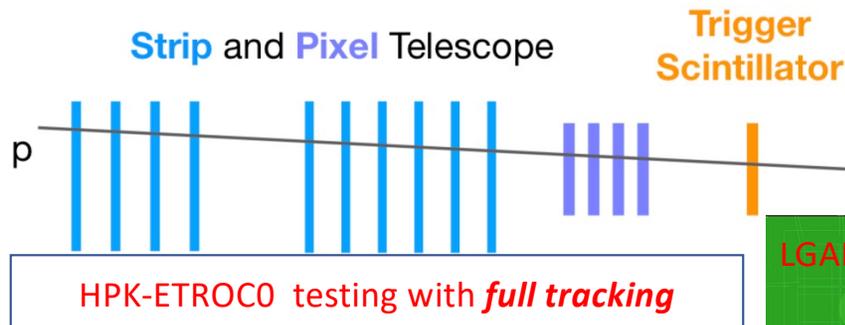
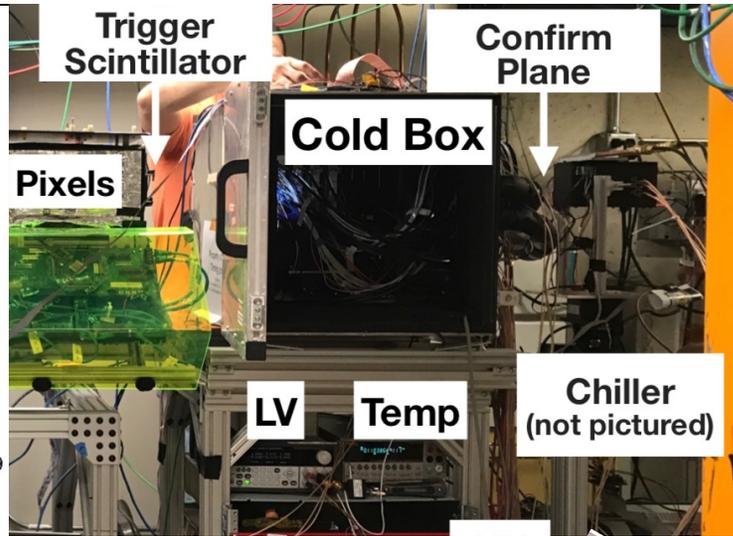
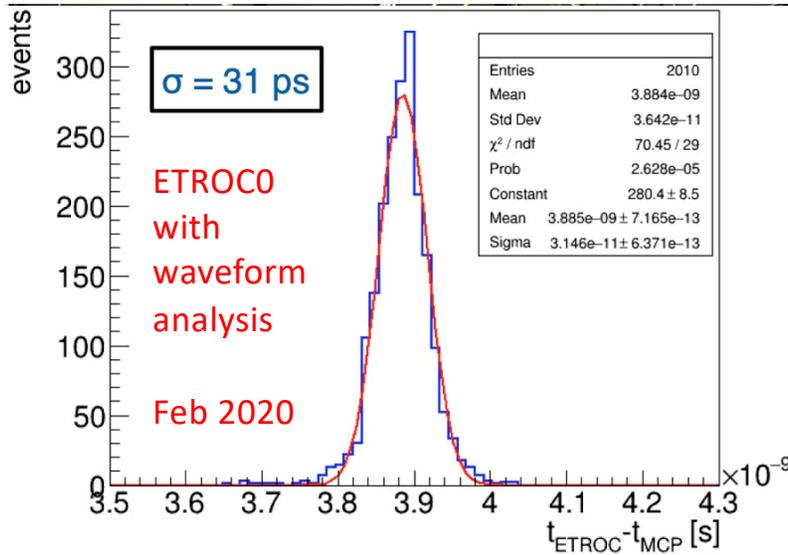




HPK-ETROCO testing with *full tracking*

- MTD Beam Test Setup at FNAL MTest
 - Independent scintillator provides trigger
 - Telescope provides proton track
 - Oscilloscope saves waveforms
 - Study $\Delta t(\text{LGAD}, \text{MCP})$

Cold box
 LGAD boards on cooling blocks MCP (Photek) time reference

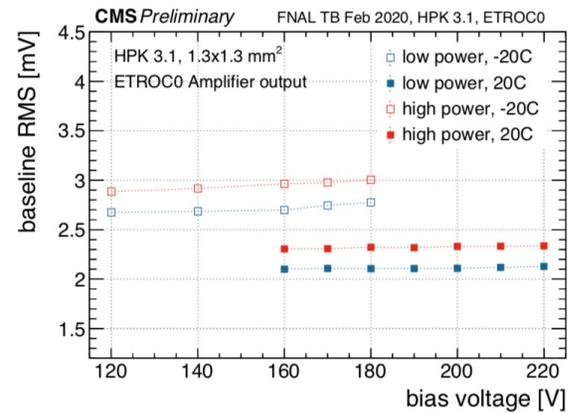
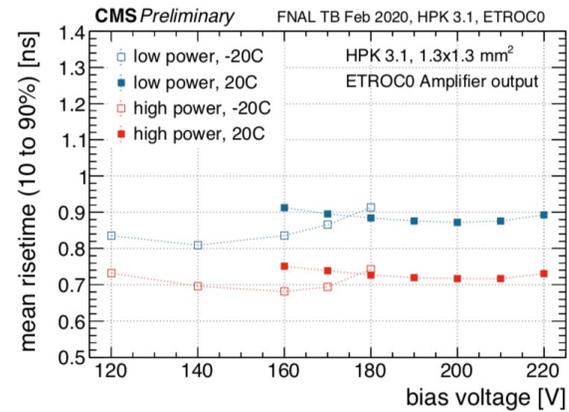
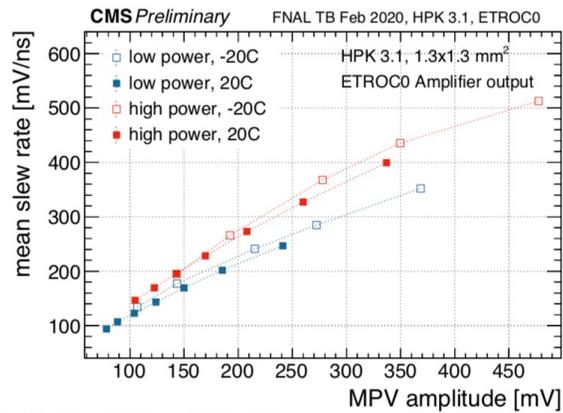


- MTD Beam Test Setup at FNAL MTest
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LGAD boards on cooling blocks MCP (Photek) time reference

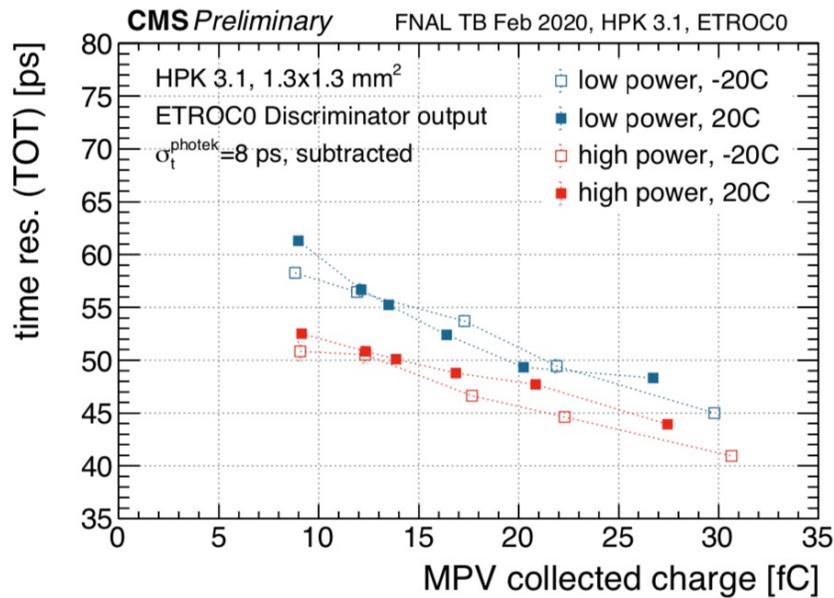
ETROCO testing beam results

Preamp performance
with beam data



ETROCO test beam result

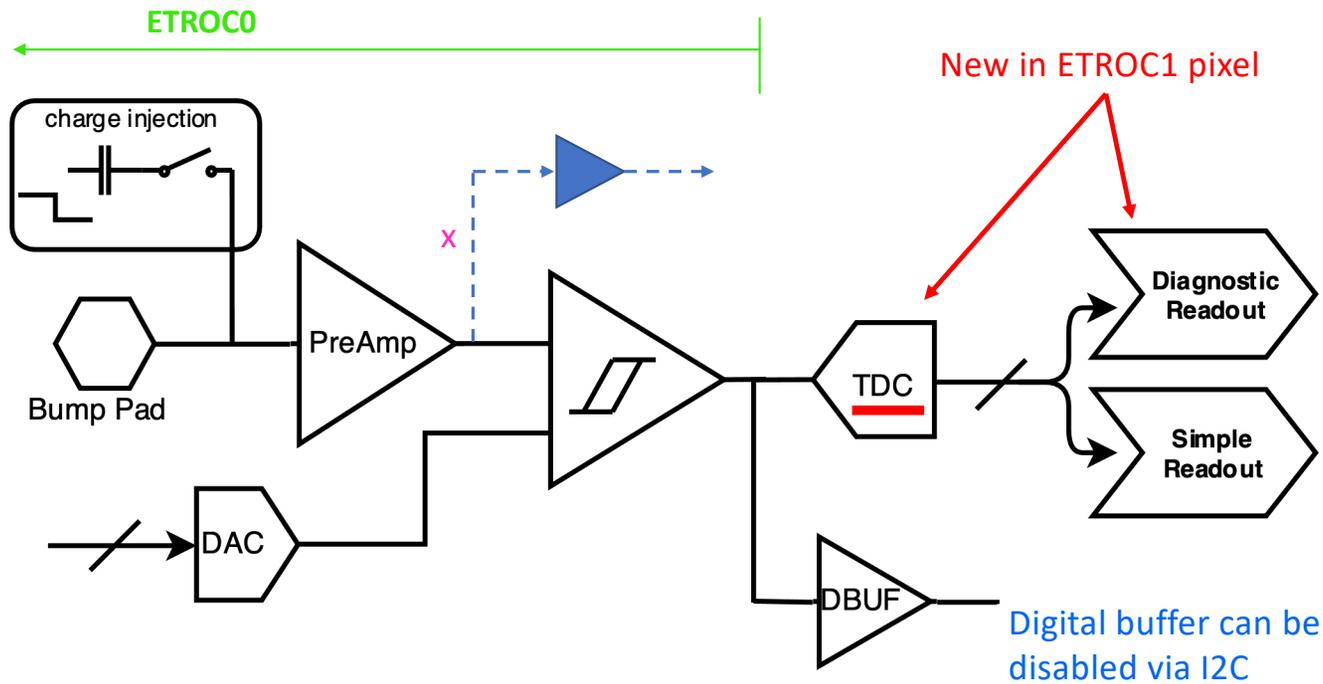
Using discriminator output



time resolution after TOT correction, with photek contribution subtracted

ETROC1 pixel: uses ETROC0 front-end

ETROC0 is used directly in ETROC1



*The TDC is brand new design (has to be ultra low power)
~ one year development effort*

ETROC1

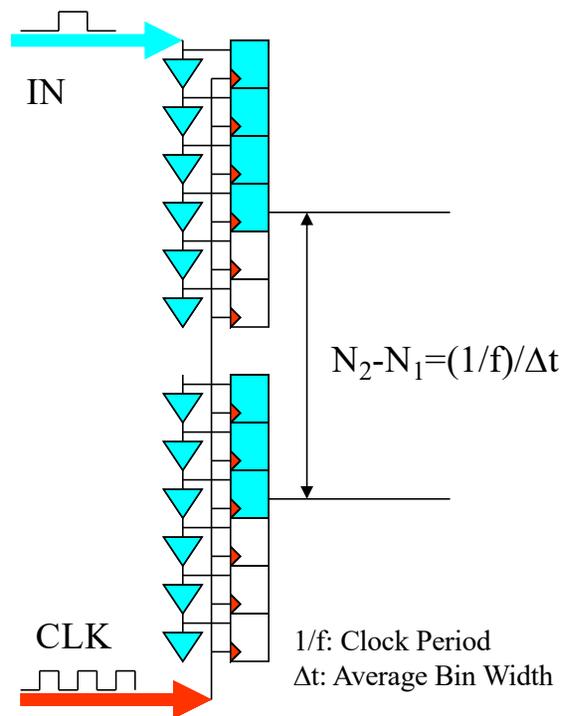
- Design started Jan 2019, submitted in Aug 2019
 - Main new component: brand new TDC
 - Specially developed for ETROC application: ultra low power consumption
 - First attempt with H tree clock distribution over 4x4 array
 - Full chain: preamp + discriminator + TDC + readout
 - *First full chain precision timing prototype*
- ETROC1 testing
 - TDC: excellent performance (<~6ps resolution)
 - Full array full chain ETROC1 charge injection: good
 - ETROC1 and 5x5 LGAD sensor bump-bonded
 - *Laser testing (on going) followed by beam testing (Dec – Feb 2021)*

A few highlights shown next, will skip some slides during the talk

ETROC1 TDC Design

- TDC requirements
 - TOA bin size $< \sim 30\text{ps}$, TOT bin size $< \sim 100\text{ps}$
 - Lower power highly desirable
 - **ETROC TDC design goal: $< 0.2\text{mW per pixel}$**
- ETROC TDC design optimized for low power
 - A simple delay line without the need for DLL's to control individual delay cells, with a cyclic structure to reduce the number of delay cells, to measure TOA & TOT at the same time
- **In-situ delay cell self-calibration technique**
 - For each hit, will use two consecutive rising clock edges to record two time stamps, with a time difference of the known 320 MHz clock period: 3.125ns
 - Crucial to reach the required precision using a tapped delay line with uncontrolled delay cells (thus lower power)

Self-Calibration: Twice-Recording Method



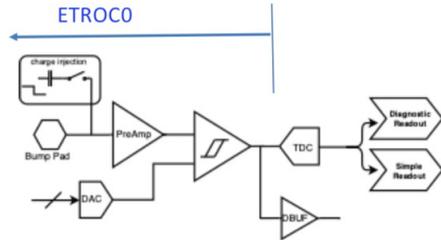
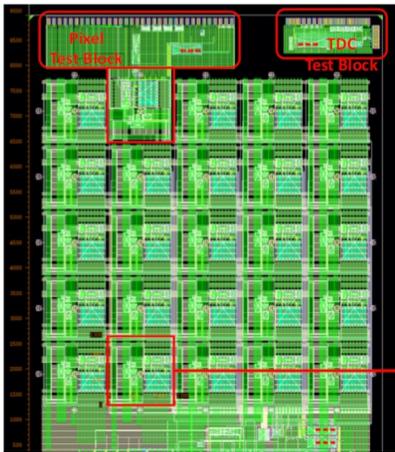
- Each hit registered twice at two consecutive clock edges
- Use known clock period for “on the fly” self-calibration of delay line

The two measurements can be used:

- to calibrate the delay.
- to reduce digitization errors.

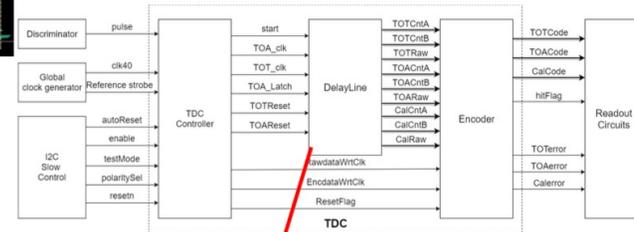
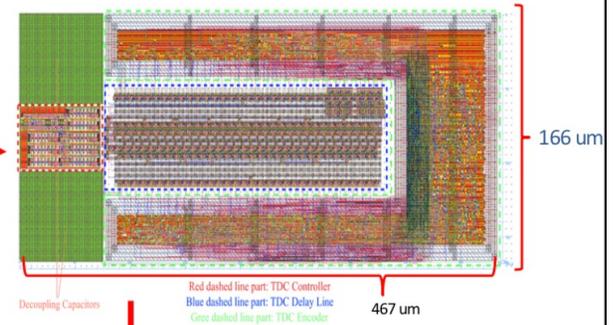
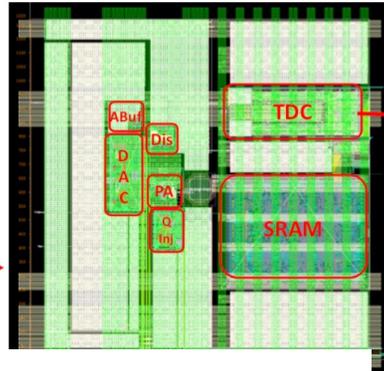
Animation by Jin-yuan Wu (FNAL EE Engineer)

ETROC1 Top Layout

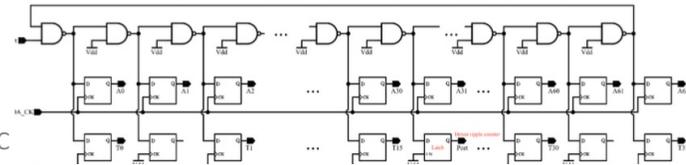


Low power TDC: <math><0.1mW</math>

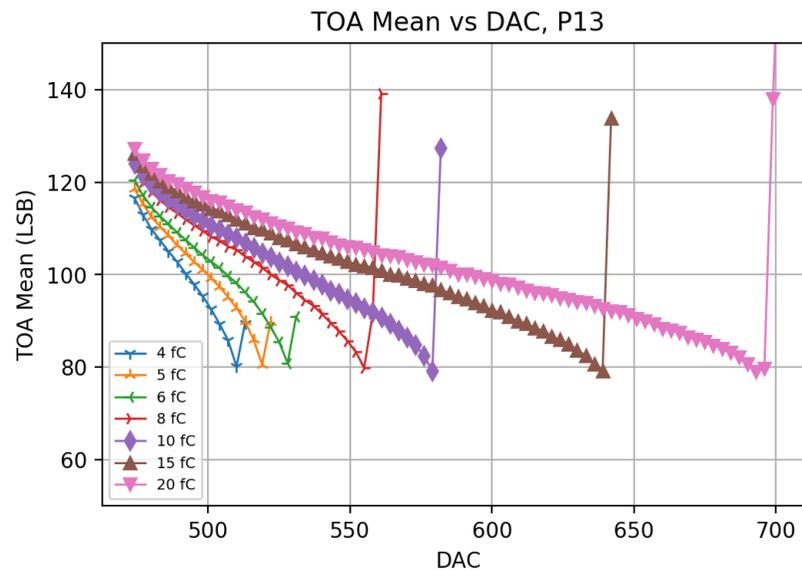
ETROC1 Single Pixel Layout



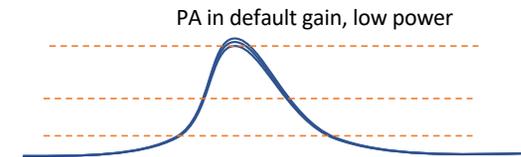
TDC core logic: gated ring oscillator



Time of Arrival (TOA) with charge injection

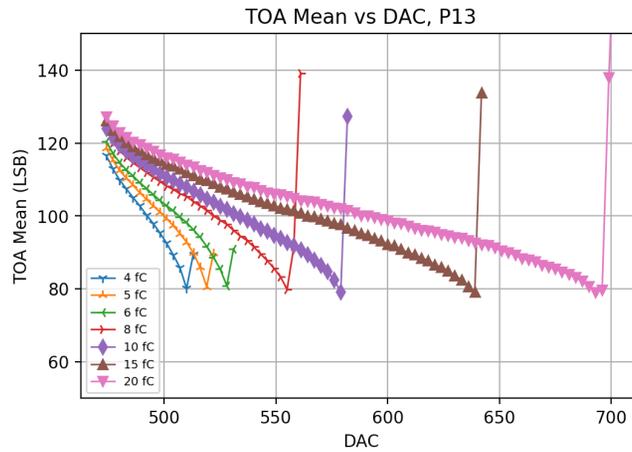


← DAC scan



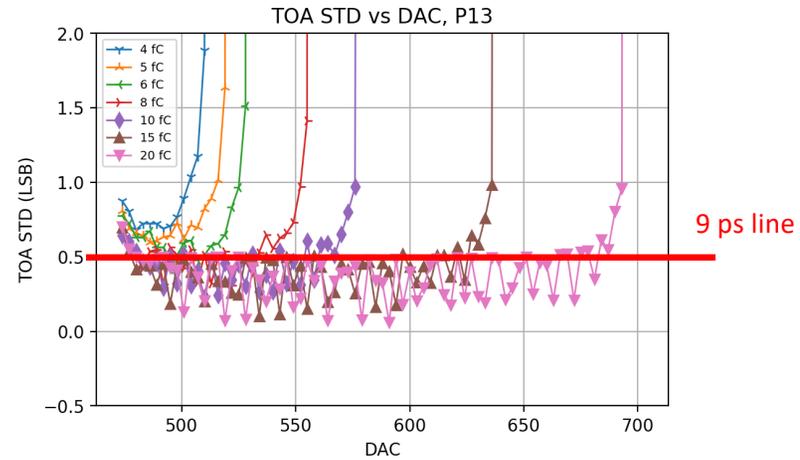
- The TOA vs the threshold look reasonable.
 - The higher the threshold, the late the discriminator fires (smaller TOA Code)
- With one feature observed:
 - When the threshold is approaching the peak, the TOA/TOT/Cal are not well determined, which is not unexpected
 - Some of the discriminator pulses didn't reach to 'high' level due to the small inputs
 - Usually accompanied by wrong Cal value
- In real operation, this would only happen to very small signal

TOA mean and std



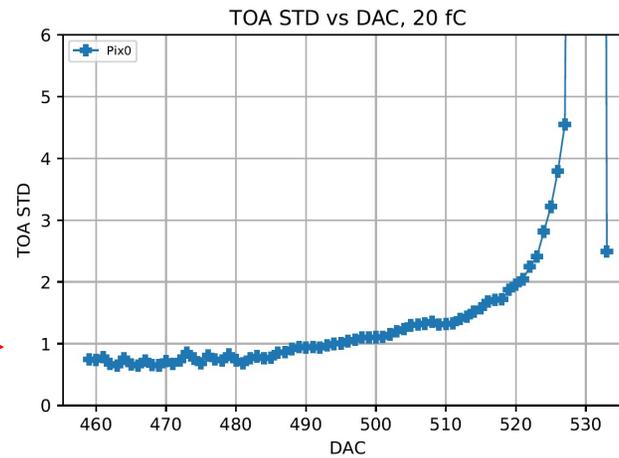
Bare ETRCO1, pixel 13

- 1 LSB = 18 ps
- PA in default gain, low power

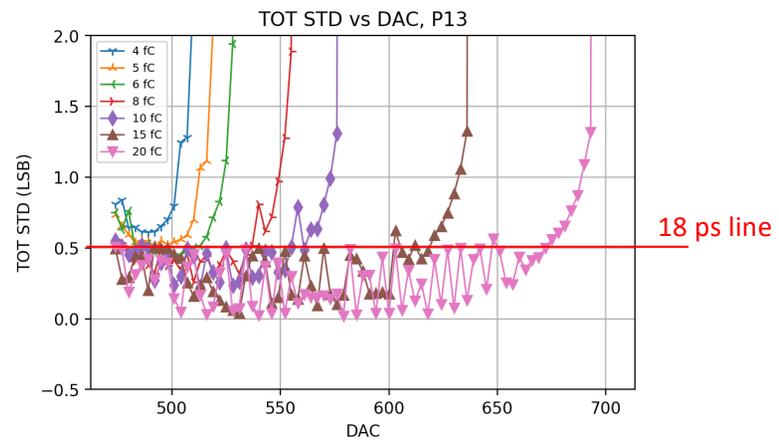
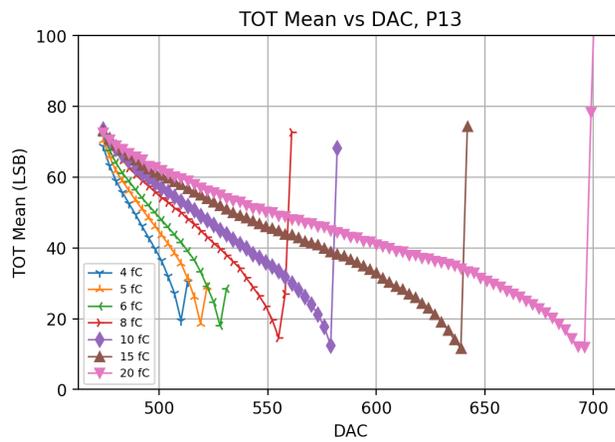


With sensor bump-bonded
On a different board/chip
(pixel 0)
Now with sensor
capacitance loaded

→
18ps line



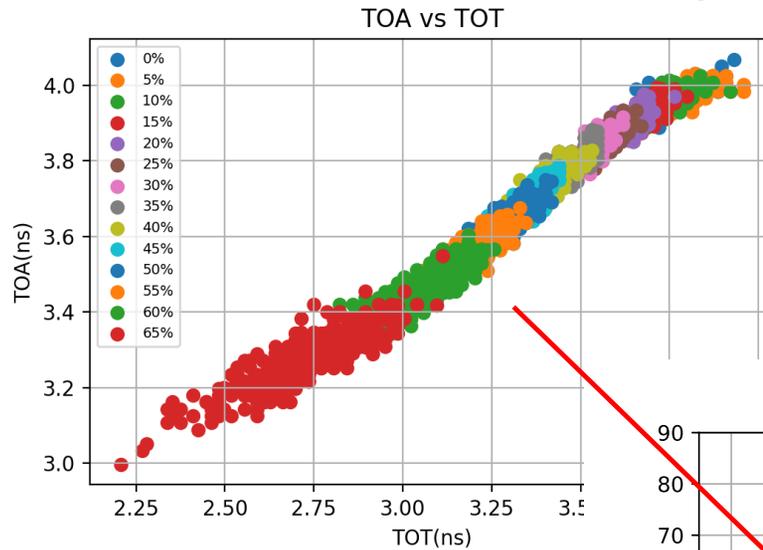
ETROC1 TOT mean and std with charge injection



- 1 LSB = 18 * 2 ps (TOT)
- Preamp in default gain, low power

Performance as expected

Jitter vs laser intensity: initial result

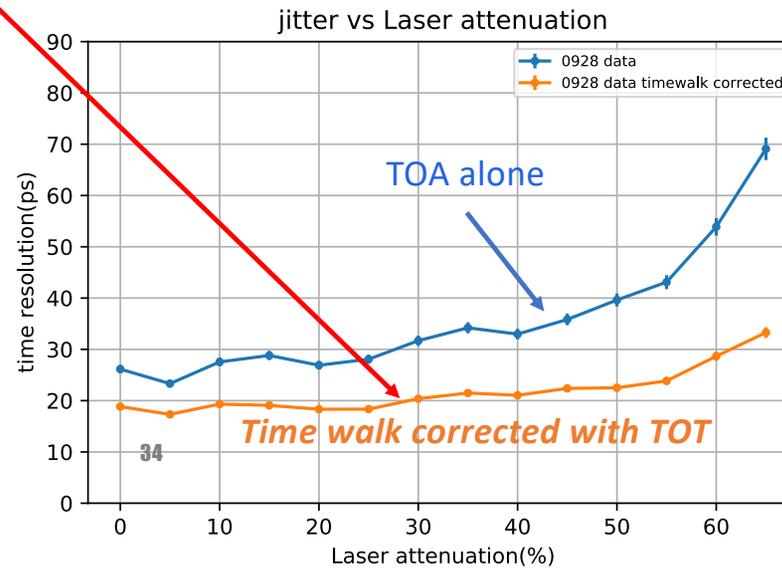


Preliminary results

Preamp at low power

Laser -> preamp -> discriminator -> TDC

Testing on going, being improved

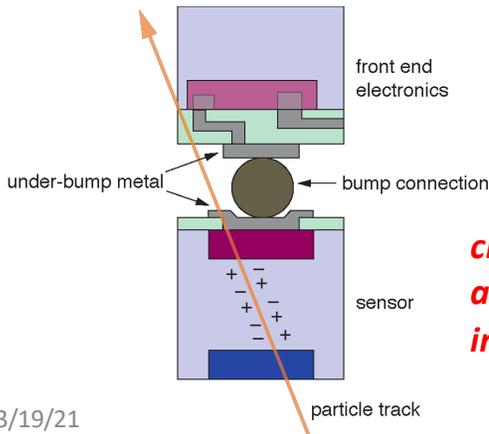


**ETROC bump-bonded to LGAD,
To handle 16x16 pixels
Each 1.3 mm x 1.3 mm**

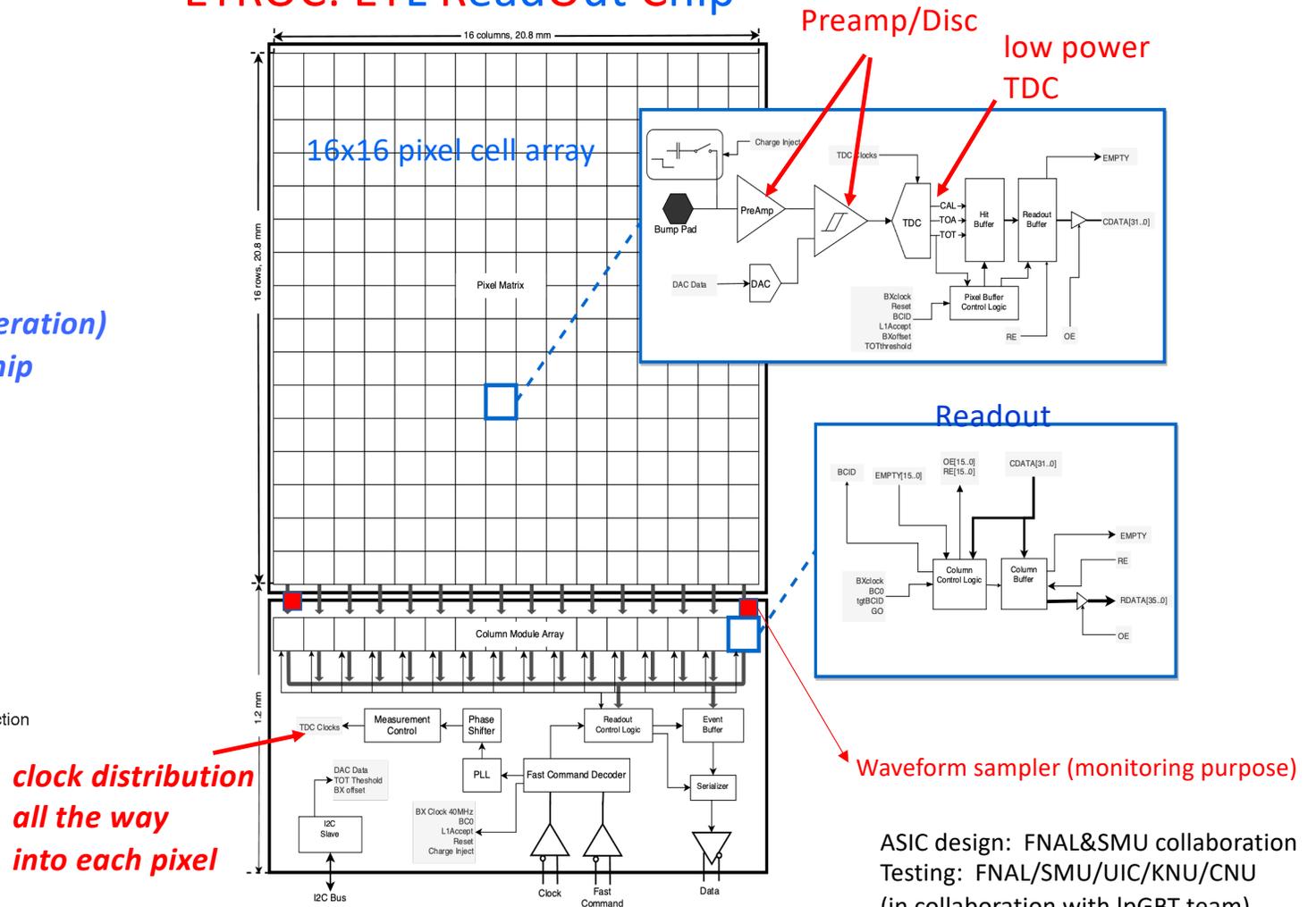
**Requirement:
ASIC contribution to
time resolution < ~40ps**

**Deal with small signal size
(down to ~6fC, at end of operation)
Power consumption < 1W/chip
(about ~2-3mW/pixel)**

**L1 buffer latency: 12.5 us
65nm**



ETROC: ETL ReadOut Chip

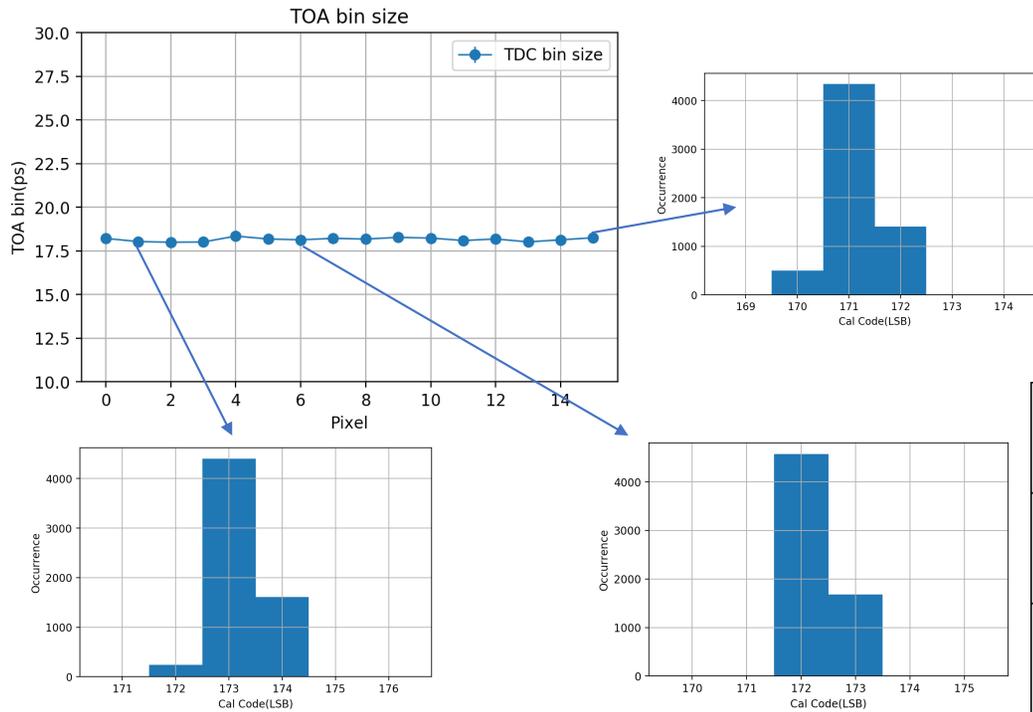


Ted Liu, ETROC

ASIC design: FNAL&SMU collaboration
Testing: FNAL/SMU/UIC/KNU/CNU
(in collaboration with IpGBT team)

Measured TOA bin size based on self-calibration (online)

320 MHz period (3.125ns) / 18ps ~ 174

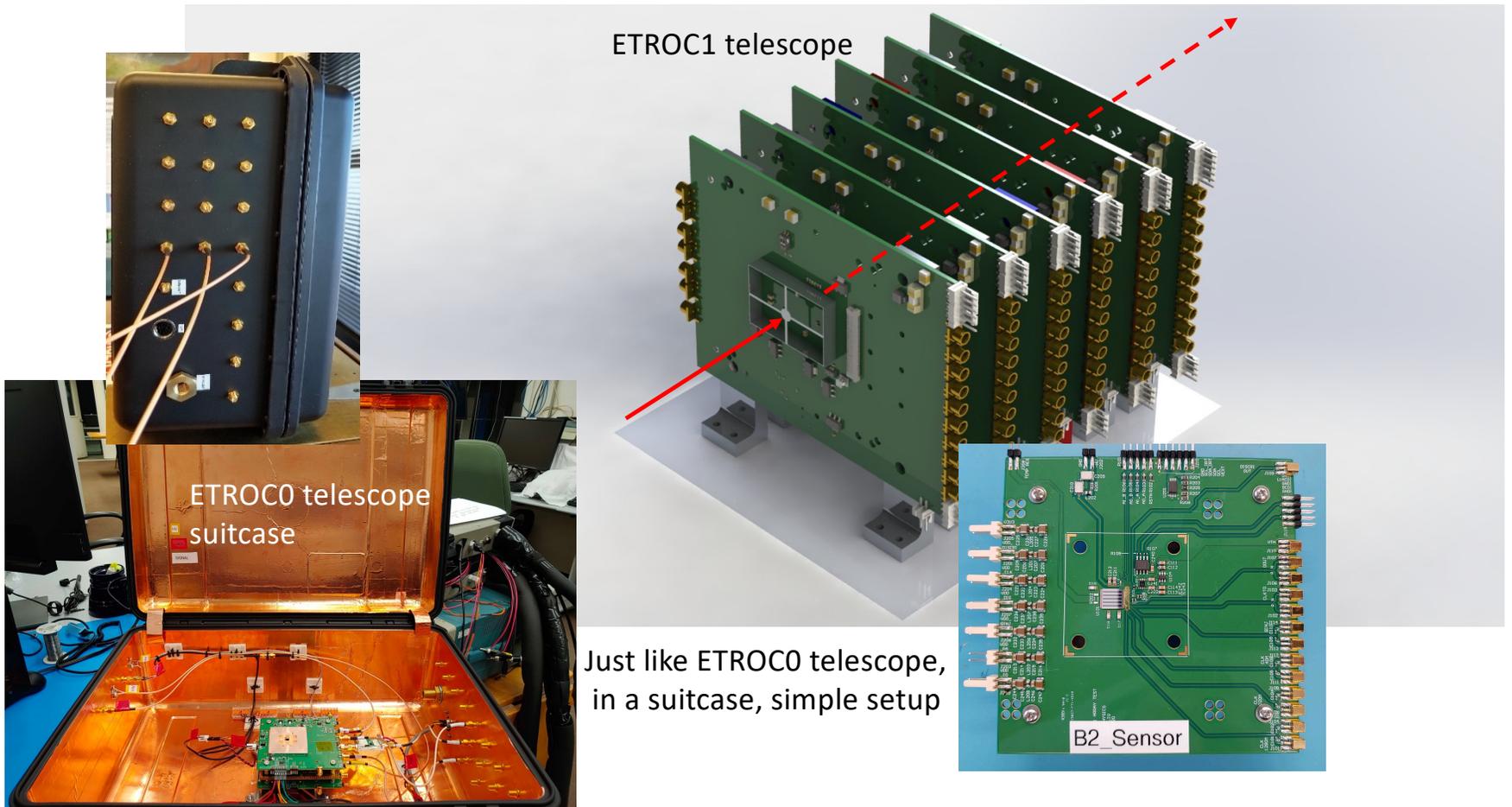


- ~18 ps bin size from the calibration code
- Good uniformity among pixels

Performance as expected

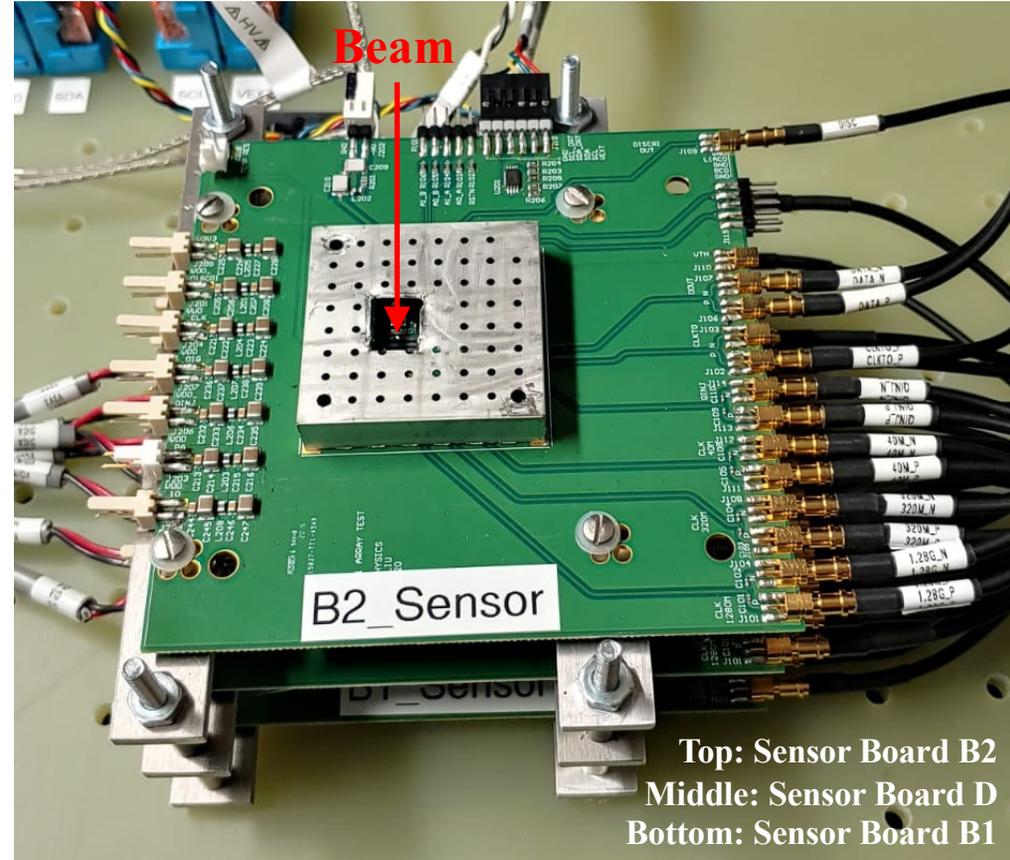
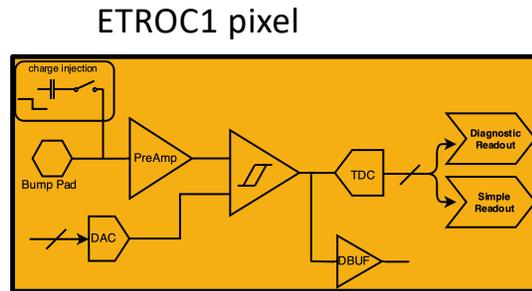
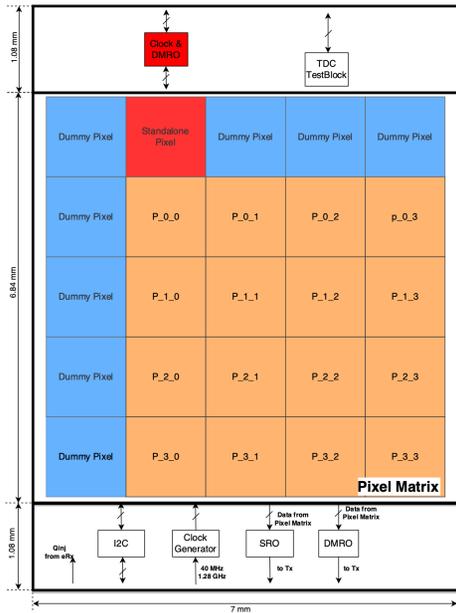
P_0_0 index: 0	P_0_1 index: 4	P_0_2 index: 8	P_0_3 index: 12
P_1_0 index: 1	P_1_1 index: 5	P_1_2 index: 9	P_1_3 index: 13
P_2_0 index: 2	P_2_1 index: 6	P_2_2 index: 10	P_2_3 index: 14
P_3_0 index: 3	P_3_1 index: 7	P_3_2 index: 11	P_3_3 index: 15
Chip peripherals			

ETROC1 Beam Telescope design



ETROC1 Beam Telescope

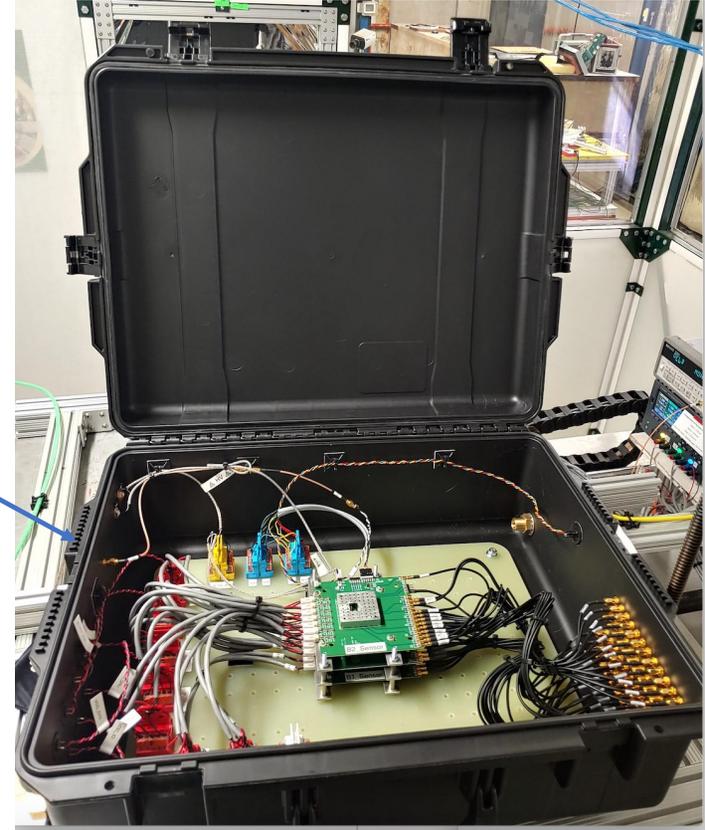
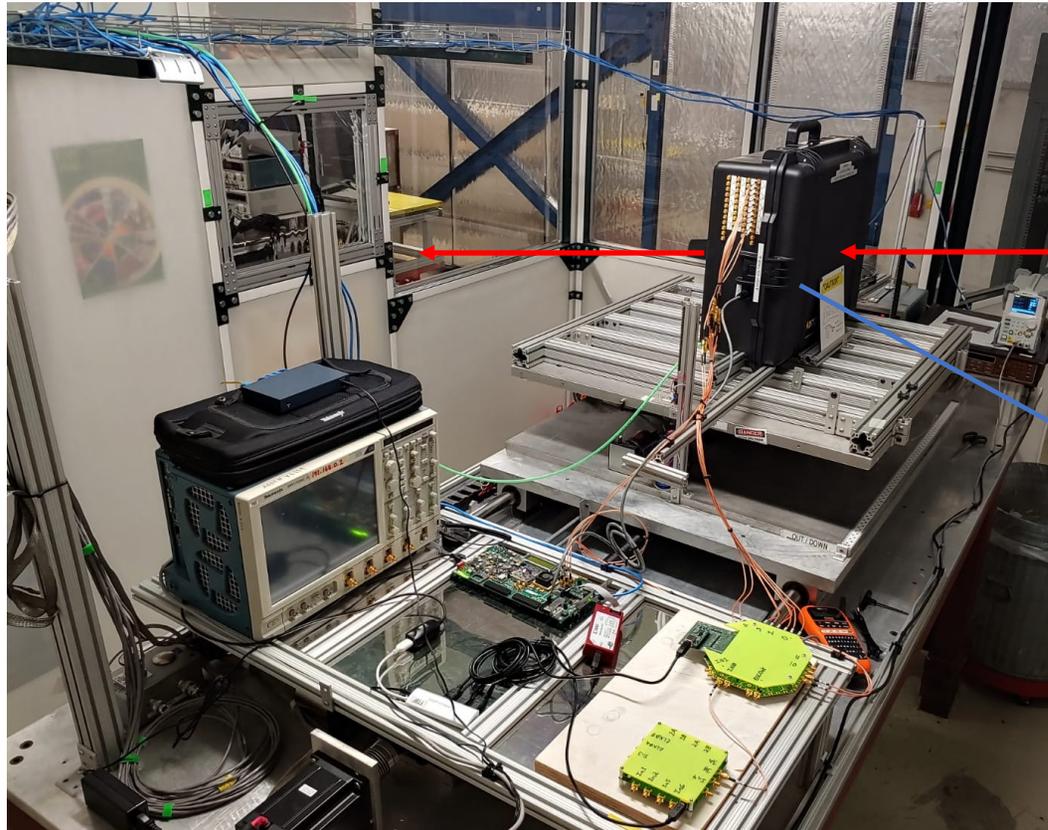
- **Hardware setup**
 - **Three-boards beam telescope**
 - Trigger on one board (e.g. B1) and record data from all three boards, and study single pixel timing resolution with $\Delta(t_i - t_j)$
 - Clock distribution and data readout among different boards must be synchronized



Top: Sensor Board B2
Middle: Sensor Board D
Bottom: Sensor Board B1

Bare ETROC1 works well: see [ETL front-end: ETROC](#) at the MTD Annual Review in 10/2020

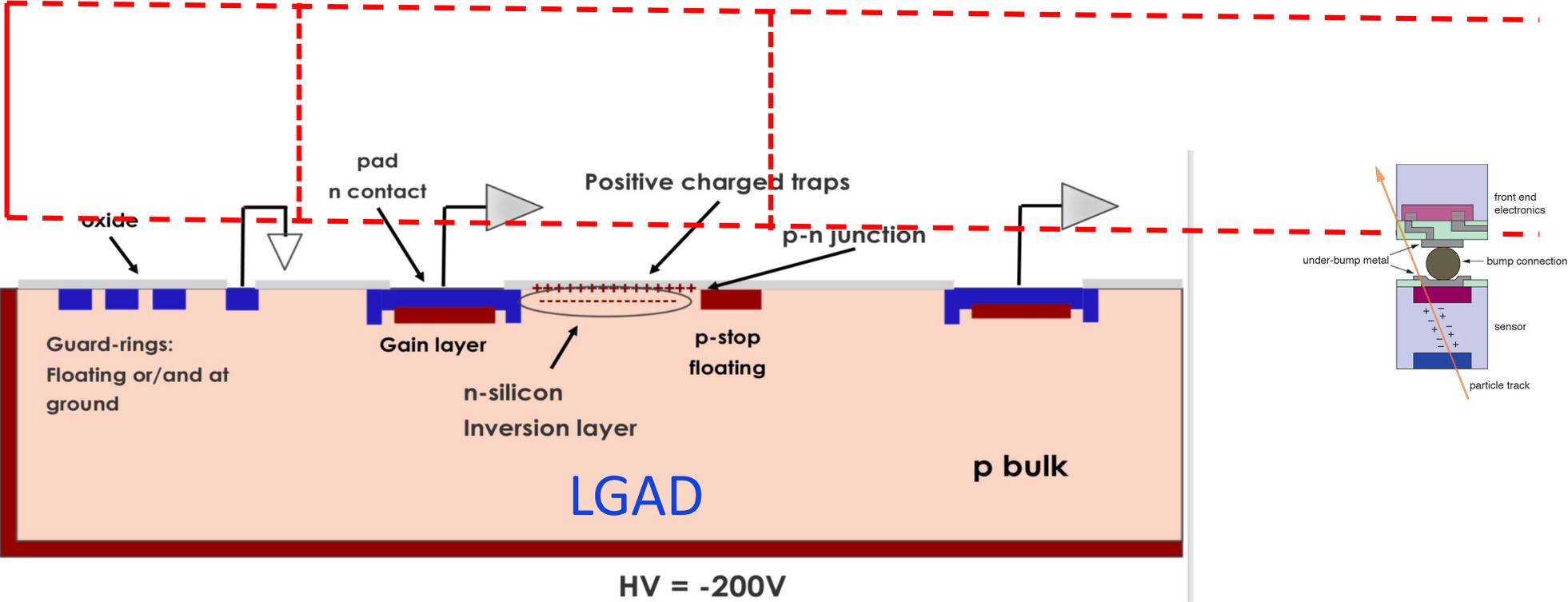
ETROC1 Beam Telescope @Fermilab FTBF



Single board DAQ system working
3-board telescope DAQ firmware is being tested now
Dedicated beam time starting this Wed (Feb 3rd, 2021)

LGAD + ETROC interface

ETROC1



Requirements for the ASIC

ATLAS HGTD: ALTIROC spec

Key requirement: Time resolution per track, combining multiple hits, is 30 ps at the start of lifetime to 50 ps after 4000 fb-1 => Time resolution /hit must be < 35 ps at start and 70 ps at the end of lifetime.

Maximum jitter (σ_{elec})	25 ps at 10 fC at the start of the HL-LHC and 70 ps for 4 fC at the end
TDC contribution	< 10 ps
Time walk contribution	< 10 ps
Clock contribution	< 15 ps
TDC conversion time	< 25 ns
Clock phase adjustment	100 ps

PAD size	1.3 x 1.3 mm ² x 50 μ m => Cdet = 4 pF
ASIC size and channels /ASIC	2x2 cm ² 15x15=225 channels/ASIC
Single PAD noise (ENC)	< 3000 e- or 0.5 fC
Minimum threshold	2 fC
Dynamic range	4 fC to 50 fC

TID Tolerance	2 MGy (inner modules replaced after each 1000 fb ⁻¹ , middle ring after 2000 fb ⁻¹)
Full chip SEU probability	< 5 % / hour

Trigger rate (latency)	1 MHz L0 (10 μ s) or 0,8 MHz L1 (35 μ s)
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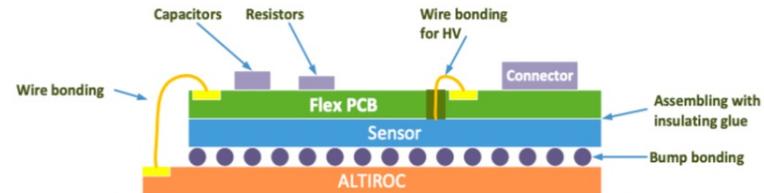
e-link driver bandwidth	320 Mbit/s, 640 Mbit/s and 1,28 Gbit/s
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Voltage and Power dissipation per ASIC	1.2V and 300 mW cm ⁻² => 1.2 W/ASIC (225 ch) or 4.4 mW/channel and 200 mW for the common part
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Main contributors to time resolution

$$\sigma_{hit}^2 = \sigma_{Landau}^2 + \sigma_{clock}^2 + \sigma_{elec}^2$$

with $\sigma_{elec}^2 = \sigma_{Time\ walk}^2 + \sigma_{jitter}^2 + \sigma_{TDC}^2$



ASIC designed in CMOS 130 nm

